

Copper Bath SLOTOCOUP CU 140

Copper Bath SLOTOCOUP CU 140 is used for plating but not for filling of blind microvias and is also well suited for metallization of through holes.

The electrolyte deposits bright copper coatings with low internal stress and good ductility and excellent metal distribution.

The metal distribution may be matched to the boards surface geometry by regulation of the current density and electrolyte composition.

Copper Bath SLOTOCOUP CU 140 is operated with three liquid additives. It can be operated with soluble as well as with insoluble anodes.

The information in this data sheet is based on laboratory as well as practical experience. Figures quoted for operating limits and replenishment quantities are for guidance. Actual values necessary will depend on the components being plated (material and geometry), their application and plating plant conditions.

Important:

Please read these instructions carefully and follow recommendations given. We reserve the right to make technical changes as necessary. In the interests of safety, please pay attention to the R- and S- phrases on the labels of the containers. The minimum shelf life of the additives is printed on the label of the container. The current IMDS number of the layer deposited from the process can be found on the internet at www.schloetter.com/downloads.

For the storage of chemical products only the TRGS 514 and TRGS 515 regulations must be followed. The Hazardous Goods Regulation (ADR/GGVS) is only valid **for transportation** and must not be applied to storage.

